

What's new@intel P. Thierry

Principal Engineer, Intel Corp

philippe.thierry@intel.com

CPU trend

Memory update

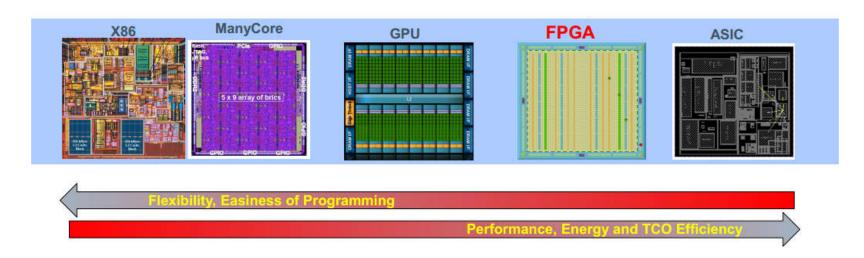
Software

Characterization

... in 30 mn

10 000 feet view





CPU : Range of few TF/s and <200 GB/s per node. Large memory footprint. Standard programing model (PM)

MIC : bootable. hundreds of threads. 3TF/s DP , 500GB/s HBM , Standard PM

FPGA : Discrete and with Xeon CPU. 1.5 TF/s A10 (now)

GenGraphics: Single socket CPU. 45W. 1.5 GF/s SP. DDR4 and eDRAM. Omp and Ocl

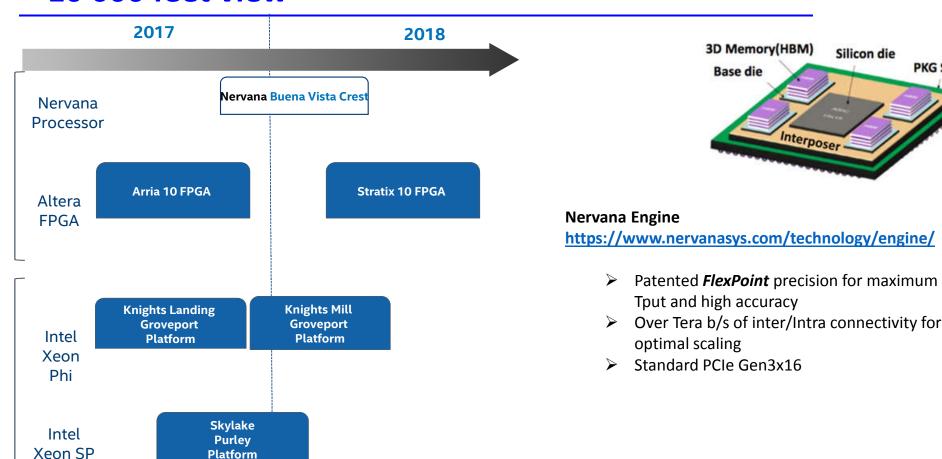
ASIC : > 50 Tops/s, HBM low level PM for now

+ SSD/ NVM + Parallel File System + HPC Software stack, Compilers, Math Libraries

10 000 feet view



PKG Substrate



RTC Workshop, Paris 2016

(2S)

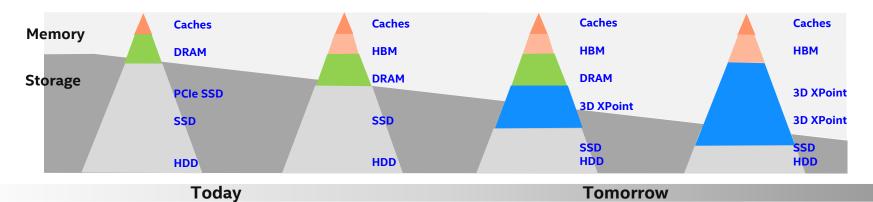
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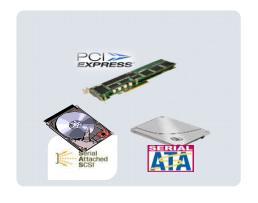
Storage Evolution

Storage class memory

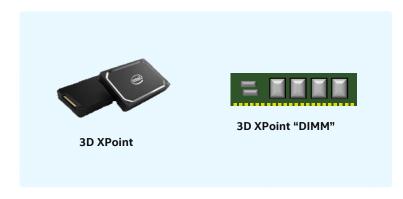


On package memory



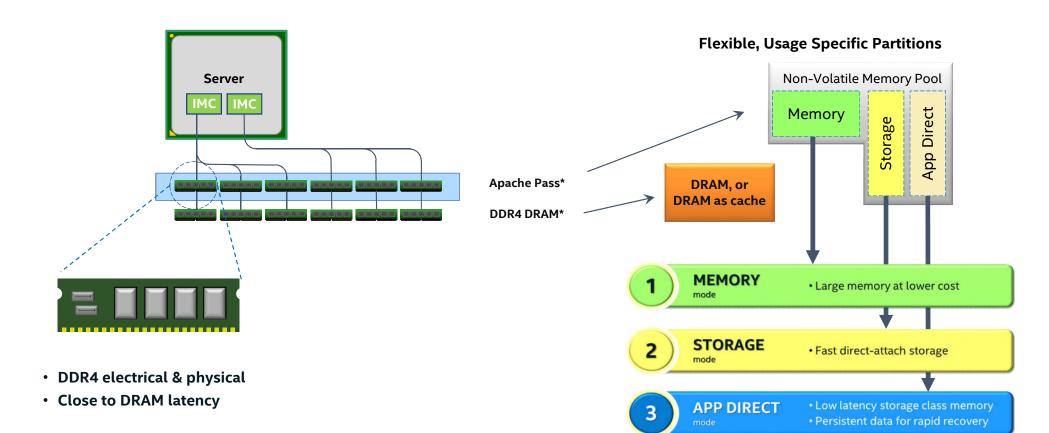






3D Xpoint : DIMM form factor







Compiler, mkl, ipp, MPI, Openmp, Opencl vtune, advisor, itac, inspector ..

CPU trend

Memory update

Software

Characterization

.. in 5 mn

MPI Performance Snapshot

Your application is OpenMP bound. High OpenMP imbalance has been identified. Use <u>Intel VTune Amplifier</u> for further analysis. Application: /nfs/inn/home/yshchyok/p/svn/testing/ts/results/2015.09.23 12.31.09/itac_testspec/vt_key_default_test_c_icc15_n2_itac_it_mps/test

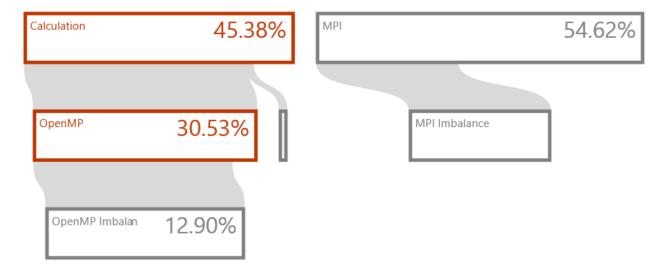
Number of ranks: 4

Used statistics: app_stat_4p28t.txt, stats_4p28t.txt

Creation date: 2015-09-28 14:58:48

Wallclock time

1.78 sec



TOP 5 MPI functions

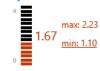
Func	<u>%</u>
Wait	71.98
Barrier	20.92
Init	3.98
Send	2.04
Recv	0.93

Memory usage



Per-process memory usage affects the application scalability.

Cycles Per Instruction Rate



This could be caused by such issues as memory stalls, instruction starvation, branch misprediction or long latency instructions.

Please use Intel® VTune™ Amplifier XE to identify the cause of this bottleneck. High values are usually bad. The CPI value may be too high.

GFLOPS

20.67

0.00%

I/O operations

I/O wait: 0.00 sec



This is the time the application spends waiting for an I/O operation to complete. High percentage of I/O wait time indicates that your application actively reads data from the storage device. This application does not spend much time on I/O operations.

Memory Bound Coefficient

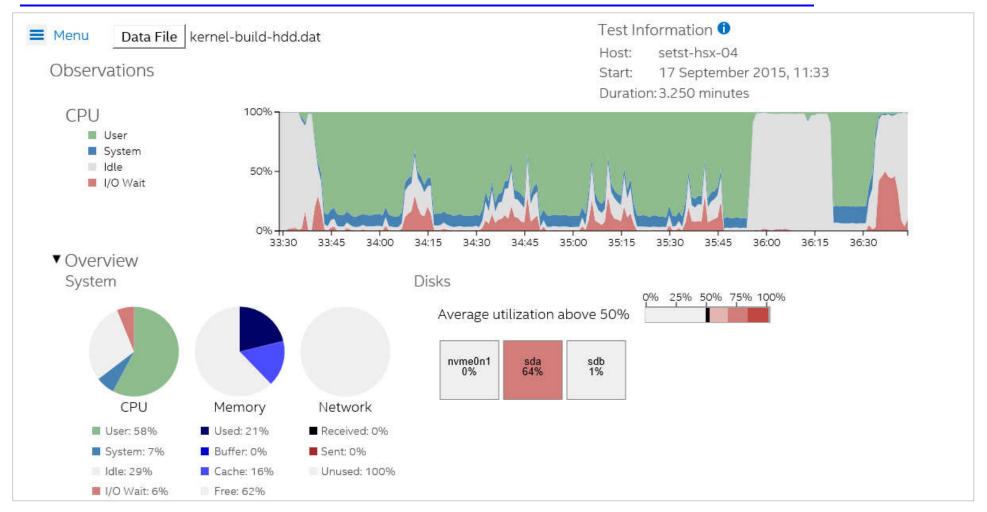


It indicates that the application doesn't spend much time waiting for data. High values are usually bad. The application is not Memory Bound.

Free download: http://www.intel.com/performance-snapshot. Also included with Intel® Parallel Studio Cluster Edition.

Storage performance snapshot



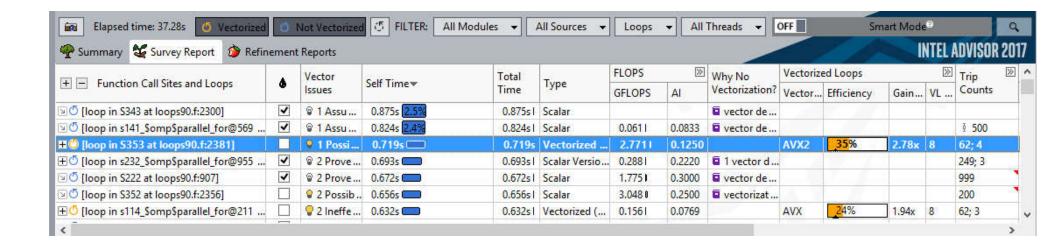


Intel® Advisor - Vectorization Advisor



The data and guidance you need:

- Compiler diagnostics + Performance Data + SIMD efficiency
- Detect problems & recommend fixes
- Loop-Carried Dependency Analysis
- Memory Access Patterns Analysis



Roofline Model. High level characterization



R.M gives the max achievable performance on a given platform

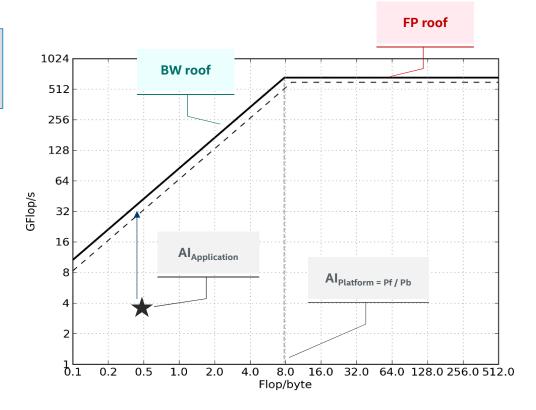
$$GFlop/s(AI) = min \left\{ \begin{matrix} p_f \\ AI \times p_b \end{matrix} \ or \ \min \left\{ \begin{matrix} xGEMM \\ AI \times StreamBW \end{matrix} \right. \right.$$

See where your application stands And what you can expect

AI: arithmetic intensity

p_f: peak FP

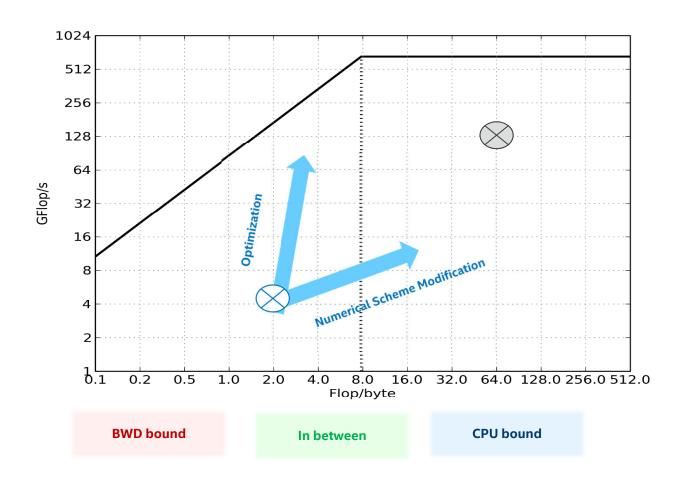
p_h: peak bandwidth



D. Lazowska, J. Zahorjan, G. Graham, K. Sevcik, "Quantitative System Performance" (1984)

Performance Characterization





Temporal roofline: Application phases identification

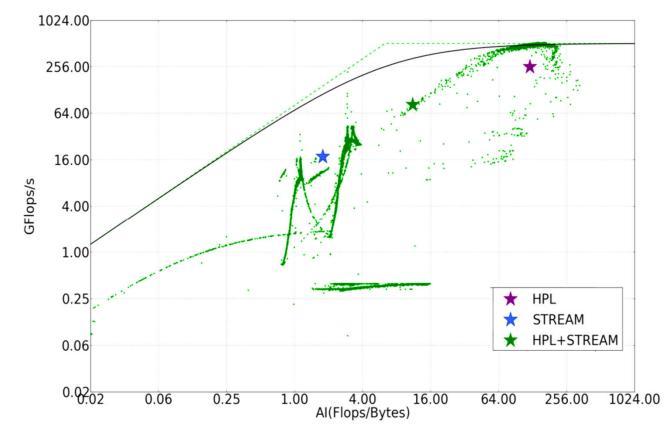


An application with 2 phases in the extremities on E5-2697 v2

- ✓ Bandwidth bound: Stream
- ✓ CPU bound: HPL

The scalar AI and flops are averaged and are not representative of the application evolution.

Temporal roofline identifies these phases distinctively.



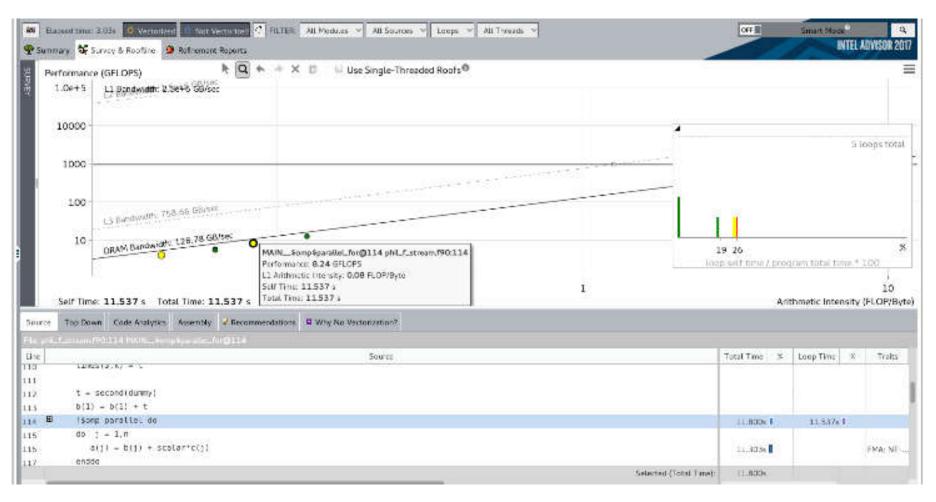
Courtesy of A. Mrabet et al. 2015

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Cache aware roofline

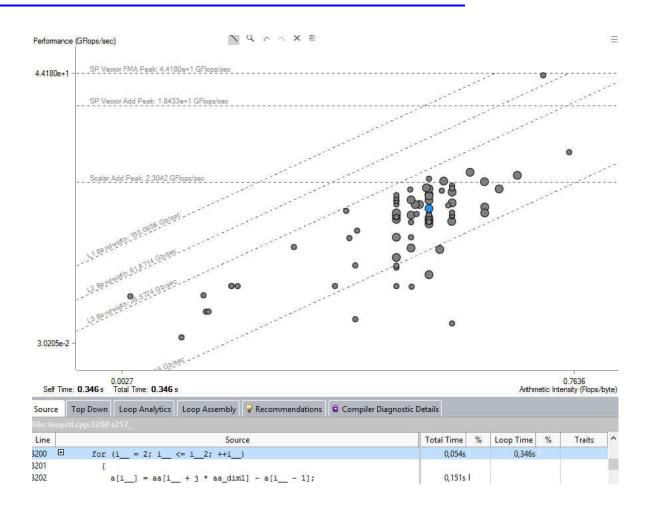




Cache aware roofline



- Know where you are vs peaks
- "what to expect"
- Per block view for the whole apps.
- Linked to source and assembly

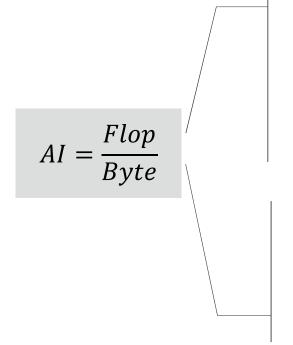


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How to collect Flops and Bytes (AI definition)





SDE

- ✓ Possible for future architectures
- ✓ Average over execution time

Hardware counters

- ✓ Not always available
- √ Vtune, PCM, LIKWID, PAPI

By hands

✓ Not always possible

Hardware counters

✓ Vtune, PCM, LIKWID, PAPI

By hands

✓ Not always possible

How to define memory demand without cache impact or latency?

DRAM demand: how many DRAM transactions a workload 'wants' to do.

versus DRAM BW: the no. of DRAM transactions completed per unit time

Programming model





Auto-vectorization (no change of code)

Compiler:

Auto-vectorization hints (#pragma vector, ...)

Compiler:

Intel® Cilk™ Plus Array Notation Extensions

SIMD intrinsic class

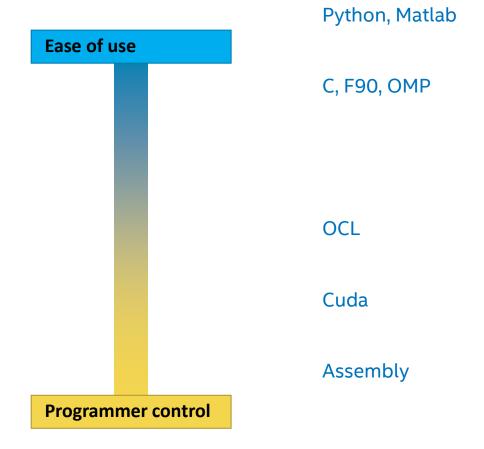
(e.g.: F32vec, F64vec, ...)

Vector intrinsic

(e.g.: _mm_fmadd_pd(...), _mm_add_ps(...), ...)

Assembly code

(e.g.: [v]addps, [v]addss, ...)





Questions?

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